



Material Content Data Sheet



Sales Product Name	SAK-XC2287-96F66L AC			Issued		29. August 2013		
MA#	MA001051816							
Package	PG-LQFP-144-4			Weight*		1469.89 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	40.856	2.78	2.78	27795	27795
leadframe	inorganic material	phosphorus	7723-14-0	0.126	0.01		86	
	non noble metal	zinc	7440-66-6	0.503	0.03		342	
	non noble metal	iron	7439-89-6	10.062	0.68		6845	
	non noble metal	copper	7440-50-8	408.558	27.80	28.52	277951	285224
wire	noble metal	gold	7440-57-5	5.975	0.41	0.41	4065	4065
encapsulation	organic material	carbon black	1333-86-4	4.909	0.33		3340	
	plastics	epoxy resin	-	132.537	9.02		90168	
	inorganic material	silicondioxide	60676-86-0	844.308	57.44	66.79	574401	667909
leadfinish	non noble metal	tin	7440-31-5	9.120	0.62	0.62	6204	6204
plating	noble metal	silver	7440-22-4	2.462	0.17	0.17	1675	1675
glue	plastics	epoxy resin	-	2.619	0.18		1782	
	noble metal	silver	7440-22-4	7.858	0.53	0.71	5346	7128
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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